



40V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
40V	$6m\Omega @ V_{GS} = 10V$	140A

Description and Applications

This MOSFET is designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Engine Management Systems
- Body Control Electronics
- DC-DC Converters

Features

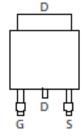
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low Qg Minimizes Switching Loss
- Low R_{DS(ON)} Minimizes On State Loss
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

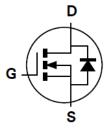
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.315 grams (Approximate)



Top View



Pin Out Top View



Equivalent Circuit

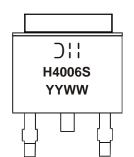
Ordering Information (Note 5)

Part Number	Case	Packaging
DMNH4006SK3Q-13	TO252 (DPAK)	2500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Dil =Manufacturer's Marking
H4006S = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year
(ex: 16 = 2016)
WW = Week Code (01 to 53)



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	40	V	
Gate-Source Voltage	V_{GSS}	±20	V	
Continuous Drain Current , V _{GS} = 10V (Note 7)	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	l _D	20 16	А
Continuous Drain Current , V_{GS} = 10V (Note 8) $T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$		I _D	140 100	А
Pulsed Drain Current (380μs Pulse, Duty Cycle = 1%)	I _{DM}	200	Α	
Maximum Continuous Body Diode Forward Current (Note 8)	Is	120	Α	
Avalanche Current, L = 0.1mH (Note 9)	I _{AS}	64	Α	
Avalanche Energy, L = 0.1mH (Note 9)	E _{AS}	208	mJ	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 6)		P_{D}	2.2	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	D	68	°C/W
Thermal Resistance, Junction to Ambient (Note o)	t<10s	$R_{\theta JA}$	29	
Total Power Dissipation (Note 7)		P_{D}	3.6	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	<u> </u>	42	°C/W
Thermal Resistance, Junction to Ambient (Note 1)	t<10s	$R_{\theta JA}$	21	
Thermal Resistance, Junction to Case (Note 8)		$R_{ heta JC}$	0.8	
Operating and Storage Temperature Range		$T_{J_i} T_{STG}$	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 10)						•	
Drain-Source Breakdown Voltage	BV _{DSS}	40		_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current, T _J = +25°C	I _{DSS}		_	1	μΑ	$V_{DS} = 40V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}		_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 10)							
Gate Threshold Voltage	V _{GS(TH)}	2		4	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}			6	mΩ	$V_{GS} = 10V, I_D = 86A$	
Diode Forward Voltage	V_{SD}		0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1.0A$	
DYNAMIC CHARACTERISTICS (Note 11)							
Input Capacitance	C _{iss}		2280	_	pF	V _{DS} = 25V, V _{GS} = 0V, -f = 1MHz	
Output Capacitance	Coss		556	_	pF		
Reverse Transfer Capacitance	Crss	_	282	_	pF		
Gate Resistance	R_g	_	1.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 6V)	Qg	l	32	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg		51	_	nC	\/ 22\/ I 86A	
Gate-Source Charge	Q_{gs}	l	9.6		nC	$V_{DS} = 32V, I_{D} = 86A$	
Gate-Drain Charge	Q_{gd}	l	20.4		nC		
Turn-On Delay Time	t _{D(ON)}		7.7	_	ns	$V_{GS} = 10V, V_{DS} = 20V,$ $R_g = 3.5\Omega, I_D = 86A$	
Turn-On Rise Time	t _R		9.3	_	ns		
Turn-Off Delay Time	t _{D(OFF)}	-	18	_	ns		
Turn-Off Fall Time	t _F		8.1	_	ns		
Body Diode Reverse Recovery Time	t _{RR}		32	_	ns	$I_F = 50A$, $di/dt = 100A/\mu s$	
Body Diode Reverse Recovery Charge	Q _{RR}	1	28	_	nC	$I_F = 50A$, $di/dt = 100A/\mu s$	

Notes:

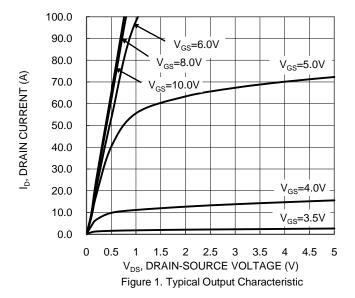
^{6.} Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout. 7. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

^{8.} Thermal resistance from junction to soldering point (on the exposed drain pad).

I. As and EAS ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.







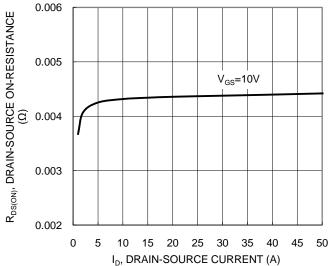


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

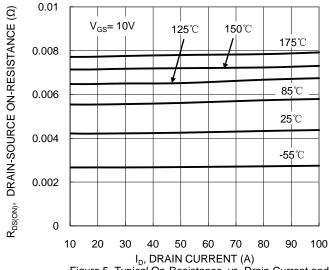
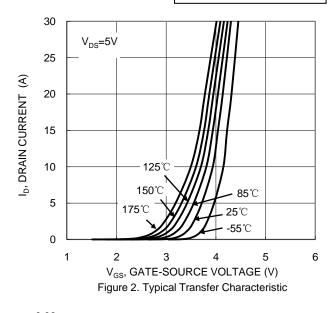
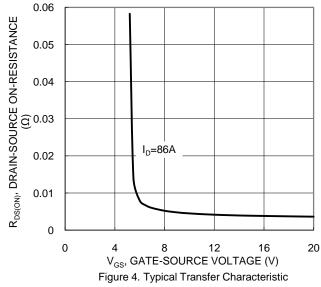


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





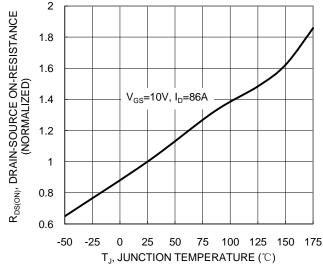


Figure 6. On-Resistance Variation with Junction Temperature



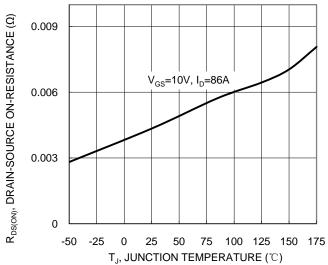
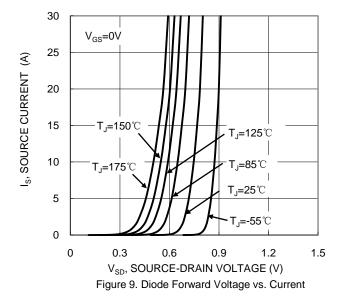


Figure 7. On-Resistance Variation with Junction Temperature



10000 f=1MHz C_T, JUNCTION CAPACITANCE (pF) $\mathsf{C}_{\mathsf{iss}}$ 1000 C_{rss} 100 0 5 10 15 20 25 30 35 40 V_{DS}, DRAIN-SOURCE VOLTAGE(V)

Figure 11. Typical Junction Capacitance

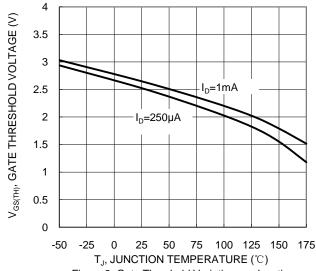


Figure 8. Gate Threshold Variation vs. Junction Temperature

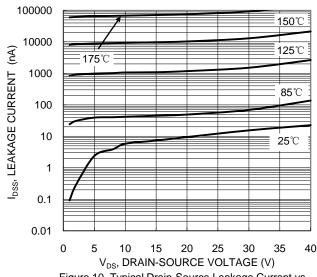


Figure 10. Typical Drain-Source Leakage Current vs. Voltage

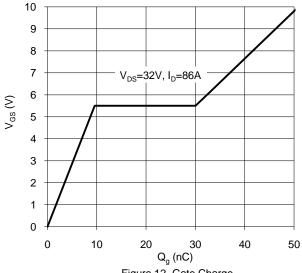
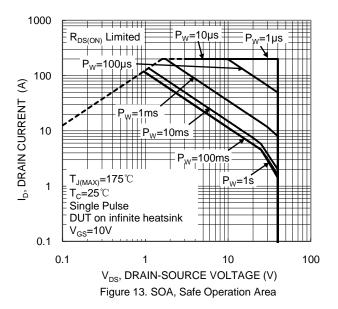


Figure 12. Gate Charge





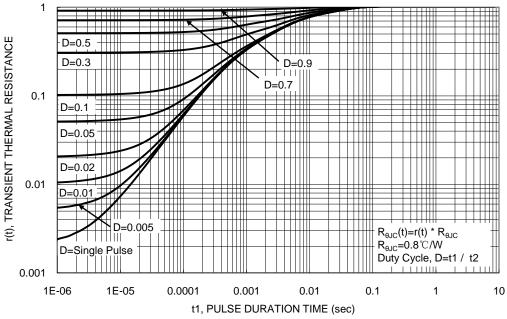


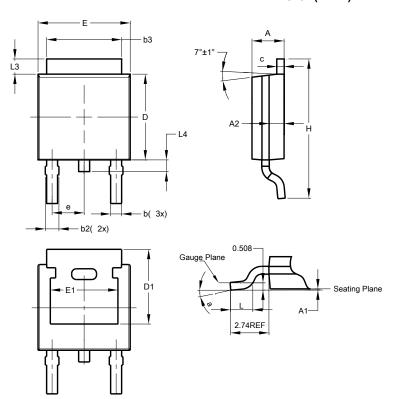
Figure 14. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)

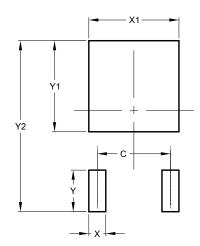


TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
O	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
е	-	-	2.286		
Е	6.45	6.70	6.58		
E1	4.32	-	-		
H	9.40	10.41	9.91		
Г	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)			
С	4.572			
Х	1.060			
X1	5.632			
Υ	2.600			
Y1	5.700			
Y2	10.700			



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